

2017 Global and Regional High Density Interconnect (HDI) PCBs Market Research Report Forecasts 2022

<https://marketpublishers.com/r/2303445DD39EN.html>

Date: July 2017

Pages: 163

Price: US\$ 2,800.00 (Single User License)

ID: 2303445DD39EN

Abstracts

This report focus on Global and regional market, providing information on major players like manufacturers, suppliers, distributors, traders, customers, investors and etc., major types, major applications from Global and major regions such as Europe, North American, South American, Asia (Excluding China), China and etc. Data type include capacity, production, market share, price, revenue, cost, gross, gross margin, growth rate, consumption, import, export and etc. Industry chain, manufacturing process, cost structure, marketing channel are also analyzed in this report.

This report provides valuable information for companies like manufacturers, suppliers, distributors, traders, customers, investors and individuals who have interests in this industry.

Major companies are as follows:

IBIDEN Group, NCAB Group, Bittele Electronics, TTM Technologies, Unimicron, ATandS, SEMCO, Young Poong Group, ZDT, Unitech Printed Circuit Board,

Major types are as follows:

4-6 Layers HDI PCBs, 8-10 Layer HDI PCBs, 10+ Layer HDI PCBs

Major applications are as follows:

Automotive (Engine Control Units; GPS; Dashboard Electronics), Computers (Laptops; Tablets; Wearable Electronics; Internet of Things - IoT), Communication (Mobile phones; Modules; Routers; Switches)

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